

Art Unit: 2829

10/685,542

SD

11/20/2004

Claims 1 through 17 are cancelled

Claim 18 (Previously Presented): A semiconductor testing device, which is used for performing a test on a semiconductor device having spherical connection terminals, comprising:

a contactor, provided with a single layer of insulating substrate, in which substrate an opening is formed at a position corresponding to a respective one of said spherical connection terminals, said contactor also being provided with a contact portion, which includes a connection portion with which said respective one of said spherical connection terminals is electrically connected, said contact portion being provided on said single layer of insulating substrate so that said connection portion is located on said opening; and

a wiring substrate, on which said contactor is mounted in a manner which permits installation and removal of said contactor onto and from said wiring substrate, said wiring substrate being provided with a first connection terminal which is provided on a first surface, on which said contactor is mounted, and is electrically connected with said contact portion, a second connection terminal which is provided on a second surface, which is opposite to said first surface, and is connected externally, and an interposer which electrically connects said first

connection terminal with said second connection terminal, wherein a projection, which comes into contact with said contact portion, is formed in said opening, a certain portion of said contact portion being moved when said respective one of said spherical connection terminals is connected with said contact portion, which certain portion is a portion extending from a position to the extending end of said contact portion, at which position said contact portion is supported by said projection.

Claim 19 (Original): The semiconductor testing device as claimed in claim 18, wherein said projection is made of an elastic material.

Claim 20 (Original): The semiconductor testing device as claimed in claim 18, wherein projections made of a conductive material.

Claim 21 (Original): The semiconductor testing device as claimed in claim 18, wherein said projection has a spherical shape.

Claim 22 (Original): The semiconductor testing device as claimed in claim 18, wherein said projection has a ring shape.

Claims 23 through 32 are cancelled